



EV832832917

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Serial No. 10/734,072
Reissue of U.S. Patent No. 6,329,213
Confirmation No. 8908
Filing Date December 10, 2003
Inventor Mark E. Tuttle et al.
Assignee Micron Technology, Inc.
Group Art Unit 2891
Examiner Caridad Everhart
Customer No. 021567
Attorney Docket No. MI40-369
Title: Methods for Forming Integrated Circuits Within Substrates

RESPONSE TO JULY 18, 2006 OFFICE ACTION UNDER 37 CFR §1.173

To: Mail Stop Amendment
Commissioner for Patents
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AMENDMENTS

Responsive to the Office Action dated July 18, 2006 in this Reissue application, Applicants amend and remark as follows. Unless otherwise indicated, deletions are [bracketed], additions are underlined to indicate changes relative to the patent.